

Features

- Top view 0402 package
- Viewing Angle = ±60°
- Compatible with infrared and vapor phase reflow solder process
- High reliability
- Ultra bright Red
- RoHS compliance

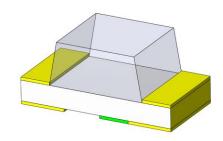
Applications

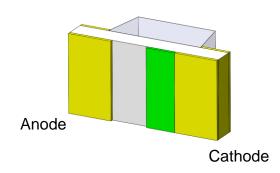
- Optical indicator.
- Switch and Symbol Display.

Description

The RP100505-ATC3 is an AlGaInP Red LED housed in a miniature SMD package. The device has a dominant wavelength of 621nm LED.

Package Outline





Schematic

Cathode
$$\longrightarrow$$
 Anode $(-)$



Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
lF	Continuous Forward Current	25	mA	
I _{FP}	Peak Forward Current	60	mA	1
V _R	Reverse Voltage	5	V	
Topr	Operating Temperature	-40 ~ +85	°C	
T _{stg}	Storage Temperature	-40 ~ +100	°C	
T _{sol}	Soldering Temperature	260	°C	2
PD	Power Dissipation at(or below) 25°C Free Air Temperature	65	mW	

Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

Optical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
lv	Luminous Intensity	I _F =20mA	74	125	200	mcd	3
λd	Dominant Wavelength	I _F =20mA	616	621	626	nm	
θ1/2	Angle of Half Intensity	I _F =20mA	•	±60	1	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward Voltage	I _F =20mA	1.7	2.1	2.5	V	4
I _R	Reverse Current	V _R =5V	-	-	1	μΑ	

Notes:

- 1. I_{FP} Conditions--Pulse Width≦ 100µs and Duty≦ 10%.
- 2. Soldering time ≤ 10 seconds.



3. Bin Range of Luminous Intensity

Bin Code	Min	Max	Unit	Condition
m2	74	89		
n1	89	100		
n2	100	130	mcd	I _F =20mA
01	130	160		
02	160	200		

Tolerance of: Luminous Intensity ±10%

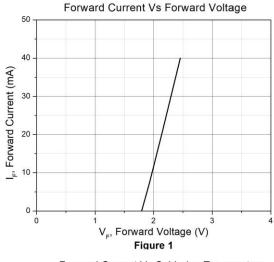
4. Bin Range of Forward Voltage

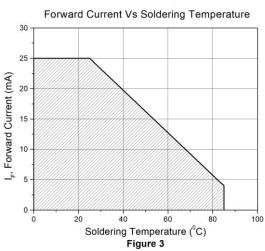
Bin Code	Min	Max	Unit	Condition	
V4	1.7	1.9		I _F =20mA	
V5	1.9	2.1	V		
V6	2.1	2.3	V		
V7	2.3	2.5			

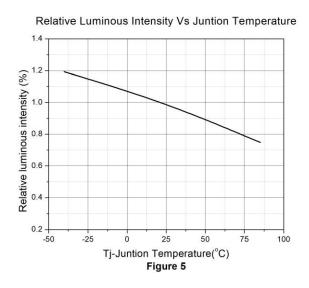
Tolerance of Forward Voltage ± 0.1 V.

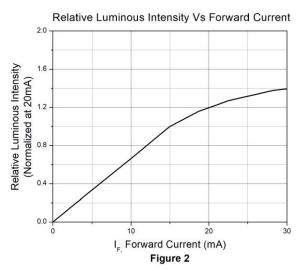


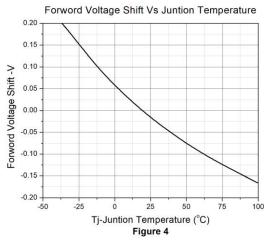
Typical Characteristic Curves

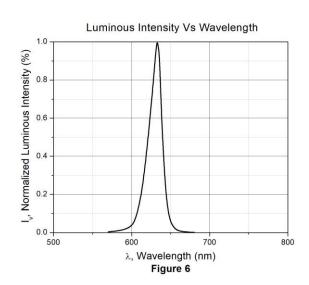






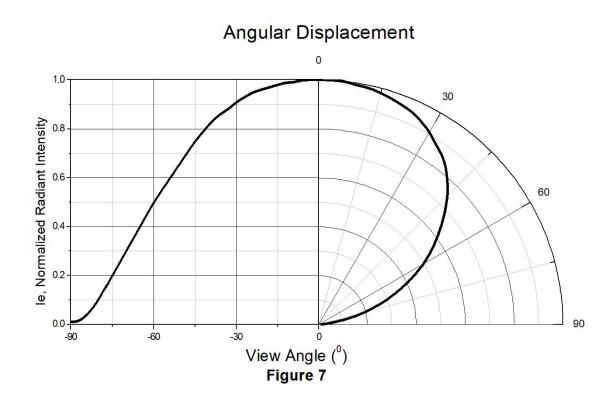






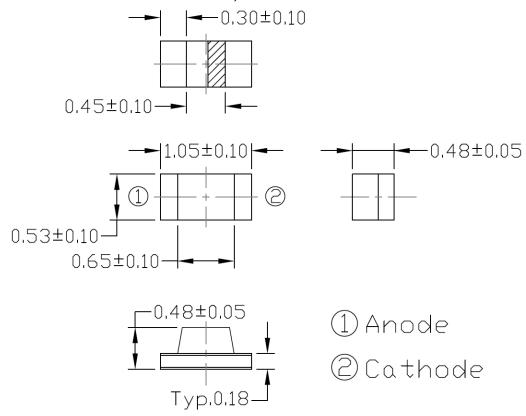


Typical Characteristic Curves



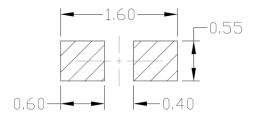


Package Dimension All dimensions are in mm, unless otherwise stated



Note: Tolerance unless mentioned is ±0.1mm.

Recommended Soldering Mask All dimensions are in mm, unless otherwise stated



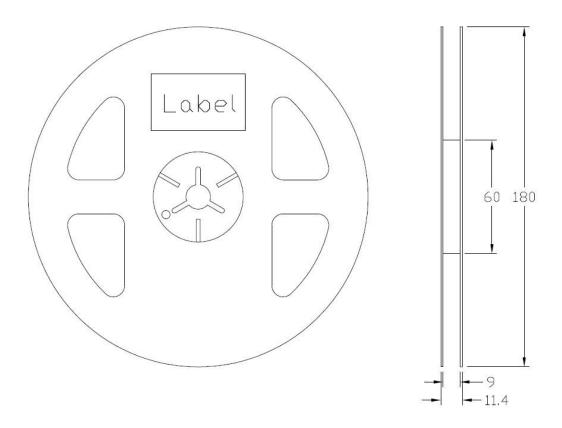
Note: Tolerance unless mentioned is ±0.1mm.

Ordering Information

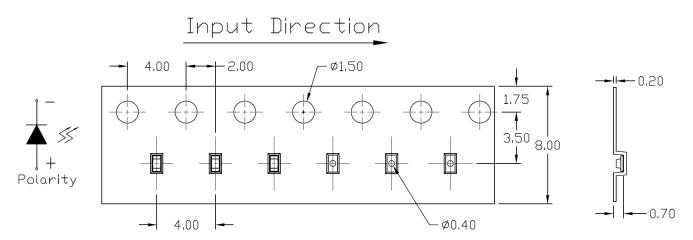
Part Number	Description	Quantity
RP100505-ATC3	Tape & Reel	3000 pcs



Reel Dimension All dimensions are in mm, unless otherwise stated



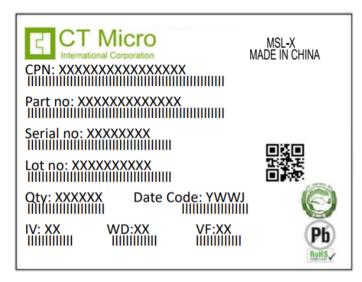
Tape Dimension All dimensions are in mm, unless otherwise stated



Note: Tolerance unless mentioned is ±0.1mm.



Label Form Specification



CPN : Customer Part Number Part no: CTM Production Number

Serial no: Production Number

Lot no: Lot number

Q'ty: Packing Quantity

Date Code: Manufacture Date IV: Bin Code of Luminous Intensity

WD : Bin Code of Dominant Wavelength

VF : Bin Code of Forward Voltage

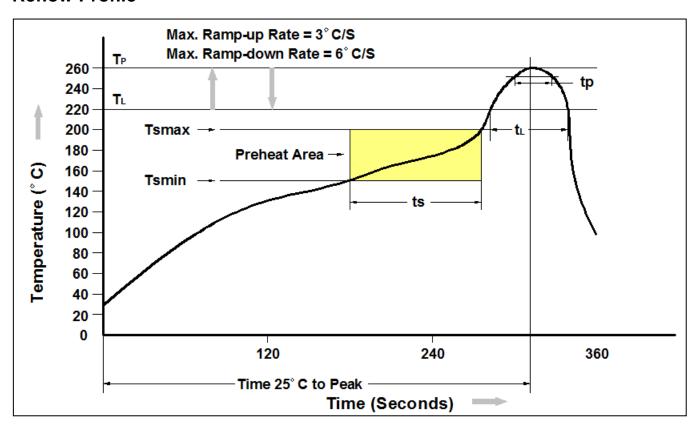
MADE IN CHINA: Production Place

Storage Condition

- 1. Do not open moisture proof bag before the products are ready to use.
- 2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening. Shelf life of non-opened bag is 12 months after the bag sealing date.
- 3. After opening the moisture barrier bag floor life is 1 year at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
- 4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t₂) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.